

# HEXFRED® Ultrafast Diodes, 100 A (INT-A-PAK Power Modules)



| PRIMARY CHARACTERISTICS              |                            |  |  |  |
|--------------------------------------|----------------------------|--|--|--|
| $V_{R}$                              | 1200 V                     |  |  |  |
| V <sub>F</sub> (typical)             | 2.5 V                      |  |  |  |
| t <sub>rr</sub> (typical)            | 150 ns                     |  |  |  |
| I <sub>F(DC)</sub> at T <sub>C</sub> | 110 A at 100 °C            |  |  |  |
| Package                              | INT-A-PAK                  |  |  |  |
| Circuit configuration                | Two diodes doubler circuit |  |  |  |

#### **FEATURES**





- Standard JEDEC® package
- · Simplified mechanical designs, rapid assembly
- High surge capability
- Large creepage distances
- UL approved file E78996
- Case style INT-A-PAK
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

| ABSOLUTE MAXIMUM RATINGS                         |                                   |   |             |       |  |
|--|-----------------------------------|---|-------------|-------|--|
| PARAMETER  | SYMBOL                            | TEST CONDITIONS                                       | VALUES      | UNITS |  |
| Cathode to anode voltage                         | $V_{R}$                           |   | 1200        | V     |  |
| Continuous forward current                       |                                   | T <sub>C</sub> = 25 °C                                | 205         |       |  |
|  | I <sub>F</sub>                    | T <sub>C</sub> = 100 °C                               | 110         | Α     |  |
| Single pulse forward current                     | I <sub>FSM</sub>                  | Limited by junction temperature                       | 800         |       |  |
| Maximum power dissipation                        | P <sub>D</sub>                    | T <sub>C</sub> = 25 °C                                | 695         | W     |  |
|  |                                   | T <sub>C</sub> = 100 °C                               | 280         |       |  |
| RMS isolation voltage                            | V <sub>ISOL</sub>                 | 50 Hz, circuit to base, all terminal shorted, t = 1 s | 3500        | V     |  |
| Operating junction and storage temperature range | T <sub>J</sub> , T <sub>Stg</sub> |   | -40 to +150 | °C    |  |

| <b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified) |                 |  |      |      |      |       |  |
|--|-----------------|--|------|------|------|-------|--|
| PARAMETER  | SYMBOL          | TEST CONDITIONS                                  | MIN. | TYP. | MAX. | UNITS |  |
| Cathode to anode breakdown voltage   | $V_{BR}$        | Ι <sub>R</sub> = 100 μΑ                          | 1200 | -    | -    |       |  |
| Maximum forward voltage  | V               | I <sub>F</sub> = 100 A                           | -    | 2.5  | 3.2  | V     |  |
|  | $V_{FM}$        | I <sub>F</sub> = 160 A                           | -    | 2.9  | 3.9  |       |  |
| Maximum reverse leakage current  | I <sub>RM</sub> | T <sub>J</sub> = 150 °C, V <sub>R</sub> = 1200 V | -    | 18   | 30   | mA    |  |



| <b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified) |                          |                        |   |      |      |      |       |
|---|--------------------------|------------------------|---|------|------|------|-------|
| PARAMETER   | SYMBOL                   | TEST CONDITIONS        |   | MIN. | TYP. | MAX. | UNITS |
| Reverse recovery time   | t <sub>rr</sub>          | T <sub>J</sub> = 25 °C |   | -    | 150  | 200  | ns    |
| Reverse recovery current  | I <sub>RRM</sub>         | T <sub>J</sub> = 25 °C | $I_F = 160 \text{ A}$<br>$dI_F/dt = 200 \text{ A/µs}$ | -    | 20   | 22   | Α     |
| Reverse recovery charge   | Q <sub>rr</sub>          | T <sub>J</sub> = 25 °C | $V_{\rm R} = 200 \text{ V}$                           | -    | 2000 | 2400 | nC    |
| Peak rate of recovery current   | dI <sub>(rec)M</sub> /dt | T <sub>J</sub> = 25 °C |   | -    | -    | 300  | A/µs  |

| THERMAL - MECHANICAL SPECIFICATIONS                    |   |                                   |   |             |       |  |
|--|---|-----------------------------------|---|-------------|-------|--|
| PARAMETER  |   | SYMBOL                            | TEST CONDITIONS   | VALUES      | UNITS |  |
| Junction operating and storage temperature range       |   | T <sub>J</sub> , T <sub>Stg</sub> |   | -40 to +150 | °C    |  |
| Maximum internal thermal r junction to case per leg    | m internal thermal resistance, to case per leg  RthJC  DC operation |                                   | 0.18  | °C ///      |       |  |
| Typical thermal resistance, case to heatsink per modul | e   | R <sub>thCS</sub>                 | Mounting surface flat, smooth and greased   | 0.05        | 0.05  |  |
| Mounting torque ± 10 % -                               | to heatsink   |                                   | A mounting compound is recommended and the torque should be rechecked after a period of 3 hours | 4 to 6      | Nm    |  |
| Woulding torque ± 10 %                                 | busbar  |                                   | to allow for the spread of the compound.  | 4 10 0      |       |  |
| Approximate weight                                     |   |                                   |   | 200         | g     |  |
|  |   |                                   |   | 7.1         | oz.   |  |
| Case style   |   |                                   |   | INT-A       | -PAK  |  |

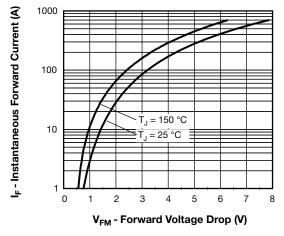


Fig. 1 - Maximum Forward Voltage Drop Characteristics

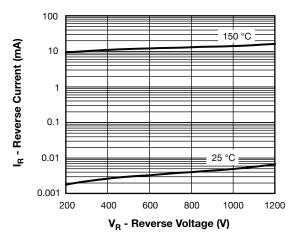


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

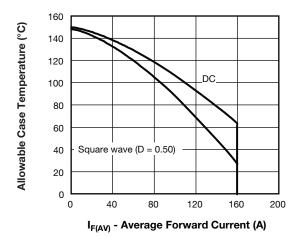


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

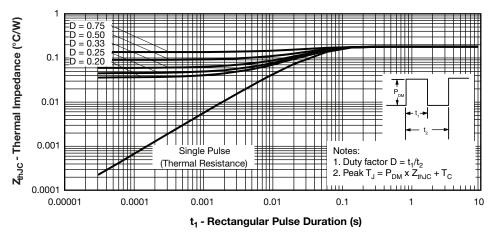


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

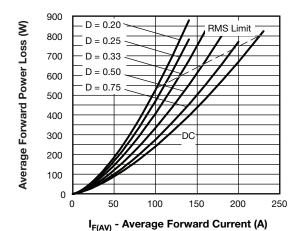


Fig. 5 - Forward Power Loss Characteristics

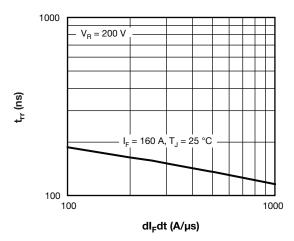


Fig. 6 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

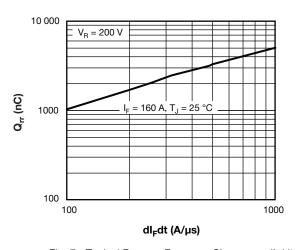


Fig. 7 - Typical Reverse Recovery Charge vs. dl<sub>F</sub>/dt (Per Leg)

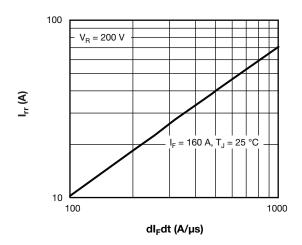
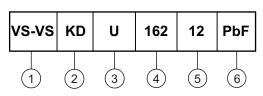


Fig. 8 - Typical Reverse Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

#### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration

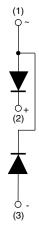
3 - U = HEXFRED® ultrafast diode

4 - Current rating

5 - Voltage rating (12 = 1200 V)

6 - PbF = Lead (Pb)-free

#### **CIRCUIT CONFIGURATION**

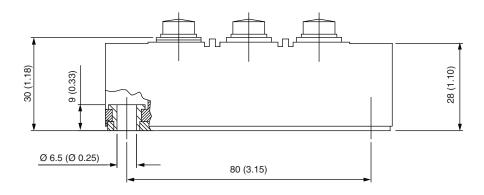


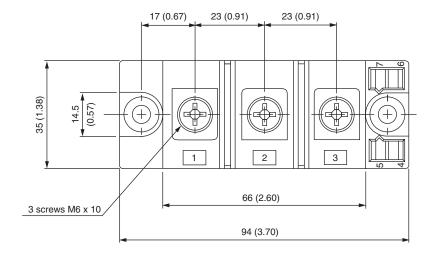
| LINKS TO RELATED DOCUMENTS |                          |  |  |  |
|----------------------------|--------------------------|--|--|--|
| Dimensions                 | www.vishay.com/doc?95254 |  |  |  |

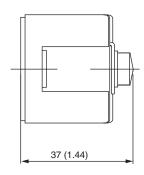


## **INT-A-PAK DBC**

## **DIMENSIONS** in millimeters (inches)









## **Legal Disclaimer Notice**

Vishay

## **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.